

	Type	Hits	Search Text	DBs	Time Stamp
1	BRS	174	semiconductor adj chip and electrodes and leads and anisotropic and (conductive or metal or wiring or gold or tin) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/30 14:34
2	BRS	2022	electrodes and leads and anisotropic and (conductive or metal or wiring or gold or tin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/05/17 18:32
3	BRS	203	electrodes and leads and anisotropic adj conductive and (conductive or metal or wiring or gold or tin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/20 19:21
4	BRS	0	6175151.uref.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/05/17 19:52
5	BRS	15	4832455.uref.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/05/17 19:57
6	BRS	8	5627405.uref.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/05/17 19:59
7	BRS	20	5608265.uref.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/05/17 20:01
8	BRS	3	257/678 and electrodes and leads and anisotropic and (conductive or metal or wiring or gold or tin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/05/17 20:03
9	BRS	5	257/684 and electrodes and leads and anisotropic and (conductive or metal or wiring or gold or tin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/05/17 20:03
10	BRS	13	257/690 and electrodes and leads and anisotropic and (conductive or metal or wiring or gold or tin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/05/17 20:05
11	BRS	8	257/692 and electrodes and leads and anisotropic and (conductive or metal or wiring or gold or tin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/05/17 20:06

	Type	Hits	Search Text	DBs	Time Stamp
12	BRS	21	257/737 and electrodes and leads and anisotropic and (conductive or metal or wiring or gold or tin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/05/17 20:07
13	BRS	2	257/767 and electrodes and leads and anisotropic and (conductive or metal or wiring or gold or tin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/05/17 20:08
14	BRS	28	257/778 and electrodes and leads and anisotropic and (conductive or metal or wiring or gold or tin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/05/17 20:10
15	BRS	6	257/779 and electrodes and leads and anisotropic and (conductive or metal or wiring or gold or tin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/05/17 20:11
16	BRS	2	257/795 and electrodes and leads and anisotropic and (conductive or metal or wiring or gold or tin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/05/17 20:11
17	BRS	34	5394490.uref.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/05/17 20:20
18	BRS	23	5822191.pn. or 5084961.pn. or 6175151.pn. or 6137183.pn. or 4832455.pn. or 5394490.pn. or 5627405.pn. or 6011310.pn. or 5550408.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/05/17 20:21
19	BRS	15	4832455.uref.	USPAT	2001/05/18 11:59
20	BRS	4798	leads and anisotropic and (conductive or metal or wiring or gold or tin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/05/18 12:55
21	BRS	189	semiconductor adj chip and electrodes and leads and anisotropic and (conductive or metal or wiring or gold or tin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/05/18 13:06

	Type	Hits	Search Text	DBs	Time Stamp
22	BRS	182	semiconductor adj chip and electrodes and leads and anisotropic and (metal or wiring or gold or tin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/05/18 16:37
23	BRS	3	5731631.pn. or 6175151.pn	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/05/18 16:41
24	BRS	5	5731631.pn. or 6175151.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/05/18 16:41
25	BRS	1	5783867.pn.	USPAT	2001/05/18 16:59
26	BRS	1037	lead and die adj pad	USPAT	2002/02/20 15:29
27	BRS	130	lead and die adj pad and heat adj sink	USPAT	2002/02/20 15:30
28	BRS	3	dual adj device and heat adj sink	USPAT	2002/02/20 15:34
29	BRS	0	dual adj device and heat and lead adj frame	USPAT	2002/02/20 15:32
30	BRS	7	dual adj device and heat and lead	USPAT	2002/02/20 15:34
31	BRS	4	dual adj device and heat adj sink	USPAT	2002/02/20 15:35
32	BRS	20	dual adj device and heat\$6	USPAT	2002/02/20 15:36
33	BRS	8	dual adj device and heat\$ and lead	USPAT	2002/02/20 15:39
34	BRS	8	dual adj device and heat and lead	USPAT	2002/02/20 15:39
35	BRS	0	dual adj device and heat adj (sink or dissipat?5 or spreader) and lead adj frame	USPAT	2002/02/20 15:41
36	BRS	124	dual adj device	USPAT	2002/02/20 15:41
37	BRS	16	4258381.uref.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/20 18:02
38	BRS	3	5834691.uref.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/20 18:57
39	BRS	3	5731631.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/20 18:53
40	BRS	2	5731631.pn. and land	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/20 18:53

	Type	Hits	Search Text	DBs	Time Stamp
41	BRS	3	5834691.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/20 18:57
42	BRS	1	"4527185".PN.	USPAT	2002/02/20 18:57
43	BRS	1	"4829362".PN.	USPAT	2002/02/20 18:57
44	BRS	1	"4862245".PN.	USPAT	2002/02/20 18:58
45	BRS	1	"4912546".PN.	USPAT	2002/02/20 18:58
46	BRS	1	"4984059".PN.	USPAT	2002/02/20 18:58
47	BRS	1	"4912546".PN.	USPAT	2002/02/20 18:58
48	BRS	1	"4984059".PN.	USPAT	2002/02/20 18:59
49	BRS	1	"5162895".PN.	USPAT	2002/02/20 18:59
50	BRS	1	"5283466".PN.	USPAT	2002/02/20 18:59
51	BRS	1	"5358906".PN.	USPAT	2002/02/20 18:59
52	BRS	1	"5479050".PN.	USPAT	2002/02/20 19:00
53	BRS	1	"5479050".PN.	USPAT	2002/02/20 19:00
54	BRS	1	"5491360".PN.	USPAT	2002/02/20 19:00
55	BRS	1	"5491360".PN.	USPAT	2002/02/20 19:00
56	BRS	1	"5663594".PN.	USPAT	2002/02/20 19:00
57	BRS	1	"4937656".PN.	USPAT	2002/02/20 19:01
58	BRS	1	"5216278".PN.	USPAT	2002/02/20 19:01
59	BRS	1	"5293072".PN.	USPAT	2002/02/20 19:02
60	BRS	1	"5663594".PN.	USPAT	2002/02/20 19:18
61	BRS	1	"5216278".PN.	USPAT	2002/02/20 19:19
62	BRS	29	(electrodes or pad or connector) and lead adj frame and anisotropic adj conductive and (gold or tin) and flip adj chip	USPAT; JPO	2002/02/20 19:28

	Type	Hits	Search Text	DBs	Time Stamp
63	BRS	383	(electrodes or pad or connector) and lead adj frame and (gold or tin) and flip adj chip	USPAT; JPO	2002/02/20 19:29
64	BRS	44	(electrodes or pad or connector) and lead adj frame and (gold or tin) and flip adj chip and anisotropic	USPAT; JPO	2002/02/20 19:32
65	BRS	206	(electrodes or pad or connector) and lead and (gold or tin) and flip adj chip and anisotropic	USPAT; JPO	2002/02/20 19:39
66	BRS	1	5731631.pn.	USPAT; JPO	2002/02/20 19:38
67	BRS	1	"5311059".PN.	USPAT	2002/02/20 19:39
68	BRS	1	"5350947".PN.	USPAT	2002/02/20 19:39
69	BRS	1	"5608262".PN.	USPAT	2002/02/20 19:39
70	BRS	18	(electrodes or pad or connector) and lead and die adj pad and flip adj chip and anisotropic and (adhesive or solder or glue)	USPAT; JPO	2002/02/20 19:44
71	BRS	52	(electrodes or pad or connector) and lead and die adj pad and anisotropic and (adhesive or solder or glue)	USPAT; JPO	2002/02/20 19:50
72	BRS	54	(electrodes or pad or connector) and lead and die adj pad and anisotropic	USPAT; JPO	2002/02/20 19:49
73	BRS	1	6121576.pn.	USPAT; JPO	2002/02/20 19:50
74	BRS	58272 4	lead	USPAT; JPO	2002/02/20 19:50
75	BRS	1426	(electrodes or pad or connector) and lead and anisotropic and (adhesive or solder or glue)	USPAT; JPO	2002/02/21 18:17
76	BRS	4	5731631.uref.	USPAT; JPO	2002/02/20 21:01

	Type	Hits	Search Text	DBs	Time Stamp
77	BRS	1	5731631.pn.	USPAT; JPO	2002/02/20 21:02
78	BRS	1	"5311059".PN.	USPAT	2002/02/20 21:02
79	BRS	1	"5350947".PN.	USPAT	2002/02/20 21:02
80	BRS	1	"5608262".PN.	USPAT	2002/02/20 21:02
81	BRS	1	"4724280".PN.	USPAT	2002/02/20 21:46
82	BRS	1	"5128746".PN.	USPAT	2002/02/20 21:46
83	BRS	1	"5214308".PN.	USPAT	2002/02/20 21:46
84	BRS	1	"5355283".PN.	USPAT	2002/02/20 21:46
85	BRS	1	"5410451".PN.	USPAT	2002/02/20 21:46
86	BRS	1	"5440169".PN.	USPAT	2002/02/20 21:49
87	BRS	1	"5502631".PN.	USPAT	2002/02/20 21:49
88	BRS	1	"5521427".PN.	USPAT	2002/02/20 21:50
89	BRS	1	"5523628".PN.	USPAT	2002/02/20 21:50
90	BRS	1	"5535101".PN.	USPAT	2002/02/20 21:50
91	BRS	1	"5567984".PN.	USPAT	2002/02/20 21:50
92	BRS	1	"5625230".PN.	USPAT	2002/02/20 21:50
93	BRS	1	"5629566".PN.	USPAT	2002/02/20 21:50
94	BRS	1	"5633535".PN.	USPAT	2002/02/20 21:51
95	BRS	1	"5641996".PN.	USPAT	2002/02/20 21:52
96	BRS	1	"5666008".PN.	USPAT	2002/02/20 21:52
97	BRS	1	"5641996".PN.	USPAT	2002/02/20 21:53
98	BRS	1	"5670826".PN.	USPAT	2002/02/20 21:53
99	BRS	1	"5677575".PN.	USPAT	2002/02/20 21:53
100	BRS	1	"5703406".PN.	USPAT	2002/02/20 21:54
101	BRS	1	"5677575".PN.	USPAT	2002/02/20 21:55

	Type	Hits	Search Text	DBs	Time Stamp
102	BRS	1	"5729051".PN.	USPAT	2002/02/20 21:55
103	BRS	1	"5804881".PN.	USPAT	2002/02/20 21:55
104	BRS	1	"5831832".PN.	USPAT	2002/02/20 21:55
105	BRS	1	"5866950".PN.	USPAT	2002/02/20 21:55
106	BRS	1	"5874784".PN.	USPAT	2002/02/20 21:56
107	BRS	1	"5877544".PN.	USPAT	2002/02/20 21:56
108	BRS	1	"5894173".PN.	USPAT	2002/02/20 21:56
109	BRS	1	"5918113".PN.	USPAT	2002/02/20 21:56
110	BRS	1	"5985043".PN.	USPAT	2002/02/20 21:57
111	BRS	1	"6025650".PN.	USPAT	2002/02/20 21:57
112	BRS	1	"5352926".PN.	USPAT	2002/02/20 21:58
113	BRS	1	"5523622".PN.	USPAT	2002/02/20 21:58
114	BRS	1	"5604379".PN.	USPAT	2002/02/20 21:58
115	BRS	1	"5677576".PN.	USPAT	2002/02/20 21:59
116	BRS	1	"5703405".PN.	USPAT	2002/02/20 21:59
117	BRS	1	"5786271".PN.	USPAT	2002/02/20 21:59
118	BRS	1	"5834844".PN.	USPAT	2002/02/20 21:59
119	BRS	1	"5844304".PN.	USPAT	2002/02/20 21:59
120	BRS	1	"5866953".PN.	USPAT	2002/02/20 21:59
121	BRS	1	"5886409".PN.	USPAT	2002/02/20 21:59
122	BRS	1	"5886415".PN.	USPAT	2002/02/20 21:59
123	BRS	1	"5946554".PN.	USPAT	2002/02/20 22:00
124	BRS	208	((electrodes or pad or connector) and lead and anisotropic and (adhesive or solder or glue)) and (land or die adj pad or island)	USPAT; JPO	2002/02/20 22:17

	Type	Hits	Search Text	DBs	Time Stamp
125	BRS	2	6204564.pn. or 5677575.pn.	USPAT; JPO	2002/02/20 22:22
126	BRS	1	(6204564.pn. or 5677575.pn.) and lead	USPAT; JPO	2002/02/20 22:25
127	BRS	0	090321303.pn.	USPAT; JPO	2002/02/20 22:25
128	BRS	0	0900321303.pn.	USPAT; JPO	2002/02/20 22:26
129	BRS	0	9321303.pn.	USPAT; JPO	2002/02/20 22:26
130	BRS	0	9321303.pn.	JPO	2002/02/20 22:26
131	BRS	0	09321303.pn.	JPO	2002/02/20 22:26
132	BRS	0	900321303.pn.	JPO	2002/02/20 22:26
133	BRS	112	Miyata near Osamu	JPO	2002/02/20 22:28
134	BRS	1	5804882.pn.	USPAT; JPO	2002/02/21 18:34
135	BRS	1	"3811186".PN.	USPAT	2002/02/21 18:32
136	BRS	1	"3893156".PN.	USPAT	2002/02/21 18:33
137	BRS	1	"4908689".PN.	USPAT	2002/02/21 18:33
138	BRS	1	"5214308".PN.	USPAT	2002/02/21 18:33
139	BRS	1	"5220200".PN.	USPAT	2002/02/21 18:33
140	BRS	1	"5283446".PN.	USPAT	2002/02/21 18:33
141	BRS	1	"5329423".PN.	USPAT	2002/02/21 18:33
142	BRS	1	"5283446".PN.	USPAT	2002/02/21 18:33
143	BRS	1	"5329423".PN.	USPAT	2002/02/21 18:33
144	BRS	1	"5352318".PN.	USPAT	2002/02/21 18:34
145	BRS	1	"5394490".PN.	USPAT	2002/02/21 18:34
146	BRS	1	"5477087".PN.	USPAT	2002/02/21 18:34
147	BRS	2	5804882.pn. or 5677575.pn.	USPAT; JPO	2002/02/21 19:01
148	BRS	1	"3871015".PN.	USPAT	2002/02/21 18:34
149	BRS	1	"5399903".PN.	USPAT	2002/02/21 18:35

	Type	Hits	Search Text	DBs	Time Stamp
150	BRS	1	"5468995".PN.	USPAT	2002/02/21 18:35
151	BRS	1	"5523622".PN.	USPAT	2002/02/21 18:35
152	BRS	1	"4183041".PN.	USPAT	2002/02/21 18:36
153	BRS	1	"4710798".PN.	USPAT	2002/02/21 18:36
154	BRS	1	"4751482".PN.	USPAT	2002/02/21 18:36
155	BRS	1	"5090609".PN.	USPAT	2002/02/21 18:36
156	BRS	1	"5381039".PN.	USPAT	2002/02/21 18:37
157	BRS	3	5804882.pn. or 5677575.pn. or 07169795.pn.	USPAT; JPO	2002/02/21 19:09
158	BRS	4	4258381.pn. or 5677575.pn. or 5834691.pn. or 6075279.pn.	USPAT; JPO	2002/02/21 19:46
159	BRS	1	5804882.pn.	USPAT; JPO	2002/02/21 19:46
160	BRS	46155	(semiconductor or chip or die or IC) and leads with (film or layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/30 14:55
161	BRS	21	"4258381"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/30 14:49
162	BRS	451	(semiconductor or chip or die or IC) and leads with (film or layer) with (recesses or indentation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/30 16:53
163	BRS	330	(semiconductor or chip or die or IC) and leads with (island or board) with (recesses or indentation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/30 16:59
164	BRS	202	(semiconductor or chip or die or IC) near (pad) with (recesses or indentation) and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/01 11:56
165	BRS	2282	257/678	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/01 11:55
166	BRS	391	257/678 and (semiconductor or chip or die or IC) near (pad or island) and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/01 12:11

	Type	Hits	Search Text	DBs	Time Stamp
167	BRS	111	257/688 and (semiconductor or chip or die or IC) near (pad or island) and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/01 12:16
168	BRS	45	257/711 and (semiconductor or chip or die or IC) near (pad or island) and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/01 12:20
169	BRS	39	257/731 and (semiconductor or chip or die or IC) near (pad or island) and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/01 12:23
170	BRS	18	257/732 and (semiconductor or chip or die or IC) near (pad or island) and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/01 12:23
171	BRS	15	257/733 and (semiconductor or chip or die or IC) near (pad or island) and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/01 12:25
172	BRS	692	257/778 and (semiconductor or chip or die or IC) near (pad or island) and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/01 12:37
173	BRS	199	257/782 and (semiconductor or chip or die or IC) near (pad or island) and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/01 12:47
174	BRS	304	257/783 and (semiconductor or chip or die or IC) near (pad or island) and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/01 12:55
175	BRS	194	257/684 and (semiconductor or chip or die or IC) near (pad or island) and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/01 13:16
176	BRS	482	257/690 and (semiconductor or chip or die or IC) near (pad or island) and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/01 16:32
177	BRS	4	5930599.pn. or 6407456.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/01 15:51
178	BRS	652	257/692 and (semiconductor or chip or die or IC) near (pad or island) and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/01 17:02
179	BRS	571	257/737 and (semiconductor or chip or die or IC) near (pad or island) and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/01 17:11

	Type	Hits	Search Text	DBs	Time Stamp
180	BRS	21	257/767 and (semiconductor or chip or die or IC) near (pad or island) and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/01 17:12
181	BRS	283	257/779 and (semiconductor or chip or die or IC) near (pad or island) and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/01 17:16
182	BRS	47	257/795 and (semiconductor or chip or die or IC) near (pad or island) and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/01 17:16
183	BRS	11	(semiconductor or chip or die or IC) and leads with (paddle) with (recesses or indentation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/02 15:47